TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOS )

# **TPC6108**

# TENTATIVE

## Notebook PC Applications Portable Equipment Applications

- Small footprint due to small and thin package
- Low drain-source ON resistance:  $RDS(ON) = 50 \text{ m}\Omega \text{ (typ.)}$
- High forward transfer admittance:  $|Y_{fs}| = 7.4 \text{ S (typ.)}$
- Low leakage current:  $I_{DSS} = -10 \mu A \text{ (max) (V}_{DS} = -30 \text{ V)}$
- Enhancement-model:  $V_{th} = -0.8$  to -2.0 V

 $(V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA})$ 

#### **Maximum Ratings (Ta = 25°C)**

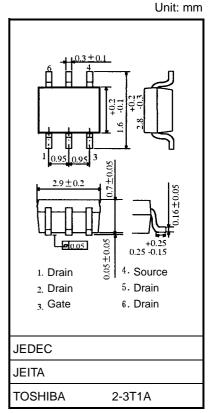
Characteristics			Symbol	Rating	Unit	
Drain-source voltage			$V_{DSS}$	-30	V	
Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ )			$V_{DGR}$	-30	V	
Gate-source voltage			V <sub>GSS</sub>	±20	V	
Drain current	DC	(Note 1)	I <sub>D</sub>	-4.5	А	
Drain current	Pulse	(Note 1)	I <sub>DP</sub>	-18		
Drain power dissipation(t = 5 s) (Note 2a)			P <sub>D</sub>	2.2	W	
Drain power dissipation(t = 5 s) (Note 2b)			P <sub>D</sub>	0.7	VV	
Single pulse avalanche energy (Note 4)			E <sub>AS</sub>	1.3	mJ	
Avalanche current			I <sub>AR</sub>	-2.25	Α	
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5)			E <sub>AR</sub>	0.22	mJ	
Channel temperature			T <sub>ch</sub>	150	ů	
Storage temperature range			$T_{stg}$	-55~150	°C	

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient(t = 5 s) (Note 2a)	R <sub>th (ch-a)</sub>	56.8	°C/W
Thermal resistance, channel to ambient(t = 5 s) (Note 2b)	R <sub>th (ch-a)</sub>	178.5	°C/W

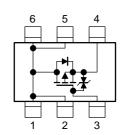
Note: For (Note 1), (Note 2), (Note 3), (Note 4) and (Note 5), please refer to the next page.

This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 0.011 g (typ.)

### **Circuit Configuration**



## Electrical Characteristics (Ta = 25°C)

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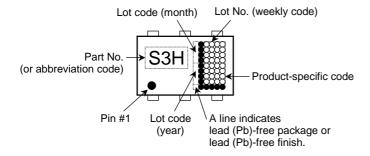
Cha	aracteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cui	rent	I <sub>GSS</sub>	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Drain cut-off curr	ent	I <sub>DSS</sub>	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	-10	μА
Drain-source breakdown voltage		V (BR) DSS	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-30	_	_	V
Dialii-source bre	ardown voltage	V (BR) DSX	$I_D = -10 \text{ mA}, V_{GS} = 20 \text{ V}$	-15 — —		_	
Gate threshold ve	oltage	$V_{th}$	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$	-0.8	_	-2.0	٧
Drain-source ON	rocietanco	R <sub>DS</sub> (ON)	$V_{GS} = -4.5 \text{ V}, I_D = -2.2 \text{ A}$	_	75	100	mΩ
Dialii-Source ON	resistance	R <sub>DS</sub> (ON)	$V_{GS} = -10 \text{ V}, I_D = -2.2 \text{ A}$	_	-     50     60       3.7     7.4     -		11122
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS} = -10 \text{ V}, I_D = -2.2 \text{ A}$			_	S
Input capacitance	Э	C <sub>iss</sub>		_	570	_	
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	75	_	pF
Output capacitan	· · · · · · · · · · · · · · · · · · ·			_	85	_	
Output capacitance  Rise  Turn  Switching time  Fall	Rise time	t <sub>r</sub>	V <sub>GS</sub> 0 V   I <sub>D</sub> = -2.2 A   O V <sub>OUT</sub>   G   S S S S S S S S S S S S S S S S S	_	3.5	_	
	Turn-on time	t <sub>on</sub>			12	_	ns
	Fall time	t <sub>f</sub>			21	_	
	Turn-off time	t <sub>off</sub>	V <sub>DD</sub> = -13 V Duty ≤ 1%, t <sub>W</sub> = 10 μs	_	70	_	
Total gate charge (gate-source plus							
Gate-source charge1		Q <sub>gs1</sub>	$I_D = -4.5 \text{ A}$	_	1.8	_	nC
Gate-drain ("mille	er") charge	Q <sub>gd</sub>		_	2.5	_	

## Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	_	_	_	-18	Α
Forward voltage (diode)		$V_{DSF}$	$I_{DR} = -4.5 \text{ A}, V_{GS} = 0 \text{ V}$			1.2	V

### Marking (Note 5)

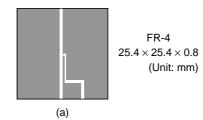
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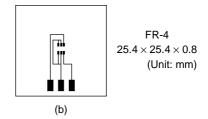


Note 1: Ensure that the channel temperature does not exceed 150 .

Note 2: (a) Device mounted on a glass-epoxy board (a) (t = 5 s)

(b) Device mounted on a glass-epoxy board (b) (t = 5 s)





Note 3:  $V_{DD} = -24~V$ ,  $T_{ch} = 25^{\circ}C$  (initial), L = 0.2~mH,  $R_G = 25~\Omega$ ,  $I_{AR} = -2.25~A$ 

Note 4: Repetitive rating: pulse width limited by max channel temperature

Note 5: on lower left of the marking indicates Pin 1.

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